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**Synthetic resin compsn. with good mould release property -
contg. silicon-contg. synthetic resin and silicone cpd. obtnd. by reacting
silicone cpd. with polypolyorganosiloxane**

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Number of Countries: 001 Number of Patents: 002

Patent Family:

Patent No	Kind	Date	Applicat No	Kind	Date	Week
JP 5086295	A	19930406	JP 9266551	A	19920325	199318 B
JP 3048738	B2	20000605	JP 9266551	A	19920325	200032

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Patent Details:

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JP 5086295	A	13	C08L-101/00	
JP 3048738	B2	13	C08J-003/12	Previous Publ. patent JP 5086295

Abstract: (Basic): JP 5086295 A

The compsn. comprises 100 pts.wt. of (A) synthetic resin and 0.01-100 pts.wt. of (B) silicone resin consisting of 30-90 mol.% of (a) RSiO1.5, 0-80 mol.% of (b) R2SiO, 1-70 mol.% of (c) R3SiO0.5 and 0-50 mol.% of (d) SiO2 (where R are opt. substd. monovalent hydrocarbon gps.). (B) consists of 50-99 mol.% of RSiO1.5 and 1-50 mol.% of R3SiO0.5 (B) is obtnd. by reacting 5-100 pts.wt. of silicone cpd. of formula (R2aSi)cZ (1) with 100 pts.wt. of polyorganosiloxane of formula R1a Si(OH)bO((4-a-b)/2) (2) and having silanol gp. in the mol.. In (1), R2 is same as R; and c is 1 or 2; when c is 1, Z is H, hydroxyl gp. or hydrolysable gp.; when c is 2, Z is -O-, -N(X)- or -S- (where X is H, 1-4C monoaliphatic hydrocarbon gp. or R23Si-). In (2), R1 is same as R; a = 0.2-2.0; b = 0.001-3; and a+b is less than 4. (B) is a thermoplastic resin which has a softening point of above 50 deg.C. and is soluble in organic solvent. (A) includes thermoplastic, thermosetting and radiation curing resins, etc., The synthetic resin compsn. is used for film, coating and moulded prods..

ADVANTAGE - The compsn. has excellent mould release property, wear resistance, moisture-proofness, processability, water repellency and high surface lustre.

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Title Terms: SYNTHETIC; RESIN; COMPOSITION; MOULD; RELEASE; PROPERTIES; CONTAIN; SILICON; CONTAIN; SYNTHETIC; RESIN; SILICONE; COMPOUND; OBTAIN; REACT; SILICONE; COMPOUND; POLY; ORGANO; POLYSILOXANE

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